

ABSTRACT

An adhesive laminate film (50) of the present invention has a heat-resistant resin layer (10), a flexible resin layer (20), and an adhesive resin layer (30) in this order, a peel strength P_0 between the heat-resistant resin layer (10) and the flexible resin layer (20), which is based on JIS Z0237 and measured using a method described below, is equal to or more than 0.01 N/25 mm and equal to or less than 2.0 N/25 mm, and a peel strength P_1 between the heat-resistant resin layer (10) and the flexible resin layer (20) after a thermal treatment of the adhesive laminate film (50) at 160°C for four hours is equal to or more than 0.05 N/25 mm and equal to or less than 1.5 N/25 mm,

(method for measuring peel strength) the adhesive laminate film (50) is attached to a silicon wafer so that the adhesive resin layer (30) comes into contact with the silicon wafer. Next, the heat-resistant resin layer (10) is peeled off from the flexible resin layer (20) using a tensile tester in a 180-degree direction under conditions of 25°C and a tensile rate of 300 mm/minute, a strength (N/25 mm) at this time is measured twice, and an average value is regarded as the peel strength.